Generate tooling holes in flexible substrate.

Clean surface, apply dry film etch resist.
Print photomechanically, develop etch and strip. Prepare surface for bonding.

Rout areas in inner layers to remove after bonding to allow access to the flexible.

Using pin or optical registration, assemble the board stack.

Bond boards in press, break out and trim to panel.

Register on to CNC drill using the pin location system to achieve position for drill programme. Drill all pth holes.

This now goes through as a multilayer board, complex product may need an additional surface prep through hole (Chemical or plasma desmear).

Profile, break out the pre routed fillers to release the flexible.

Generate tooling holes in inner layers.

Clean surface, apply dry film etch resist.
Print photomechanically, develop etch strip. Prepare surface for bonding.

Optional AOI inspection.

Telephone: 01902 606000
www.clarydon.com